

the thermosetting resin is provided by the thermosetting adhesive.

38. An electronic component mounting apparatus as claimed in claim 13, wherein

the positional alignment device and the bonding device are constructed of one device.--.

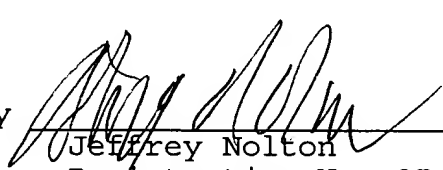
R E M A R K S

The present Preliminary Amendment is submitted to delete the multiple dependency of various of the claims thereby reducing the PTO filing fee.

Respectfully submitted,

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